

# Blanking and Lamination

**Hard Material Solution for  
High Speed Electronic Stamping**

Solution for Copper Alloy and Stainless Steel Stamping



### CBCT NF and UF Series

Electronic parts for EV and Mobile phone which include connectors and IC frames etc. , are mainly composed of metal alloy such as Cu-P, Cu-Ni and S.S.

With using our specialized NF and UF grade, the tool life as well as the CP ratio can be highly increased.

### Advantages of NF and UF Series

#### 1. Increase Tool Life:

NF and UF series has combined the high hardness and high toughness which help to increase the wear resistance and shock resistance of the tools.

#### 2. Increase Tools Machinability and Stability:

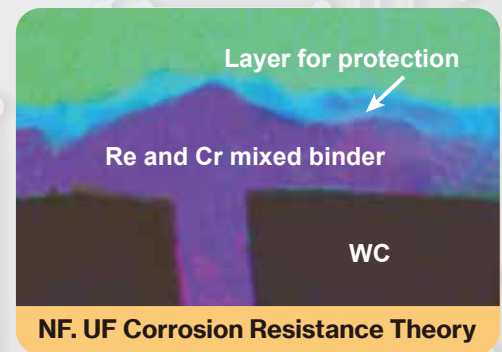
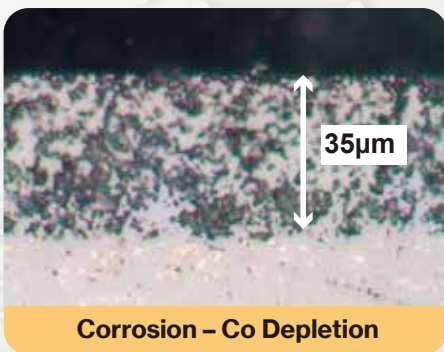
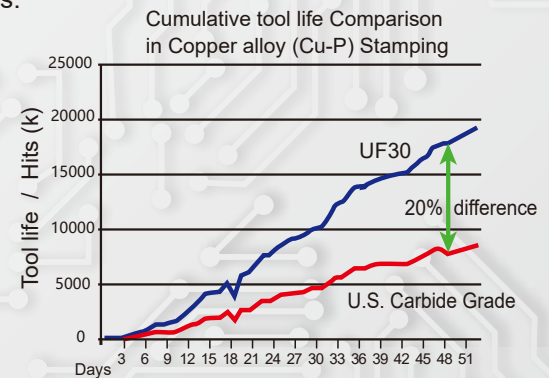
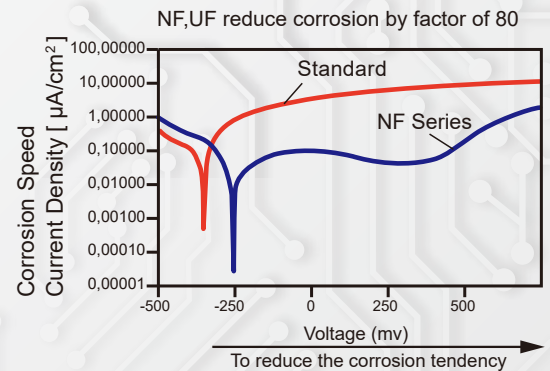
With the improved grade toughness, chip off problem on the tools can be highly reduced.

#### 3. Grade Consistency

With the extra Sinter-HIP process on the carbide, the grade consistency , hardness gradient and thus wear resistance are much improved.

#### 4. Corrosion Resistance:

NF and UF series will reduce corrosion issue on the tool when expose to corrosive substances. This avoid sticking of Cu onto the tool surface during stamping and thus surface finishing are much improved.



### Solution for Electronics Stamping (Cu Alloy, S.S ) Universal Grade – UF30

#### Characteristics:

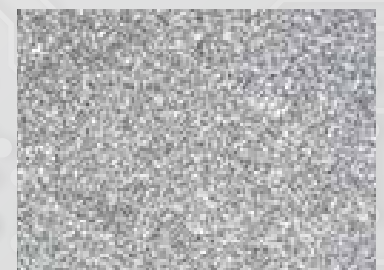
- ◆ Submicron, High Wear Resistance, High Toughness
- ◆ High TRS (Increase the strength of punch)
- ◆ Corrosion Resistance

#### Application:

- ◆ All kinds of Electronics punch for stamping, folding , drawing process
- ◆ For Cu alloy (Cu-P, Cu-Ni etc.) , <0.8mm S.S Electronics parts.
- ◆ For small punch and normal dies parts
- ◆ Good for all kinds of machining e.g. WEDM, Grinding , PG.

### UF, NF series Characteristics Figure - Solution for Electronics Stamping

Char.	Unit	UF30	NFS26	NFS16
Hardness	HRA	91	90.5	92
TRS	kgf/mm <sup>2</sup>	420	350	350
Toughness	MPam <sup>1/2</sup>	11.8	12	9.5
Density	g/cm <sup>3</sup>	13.8	14.08	14.56



UF30